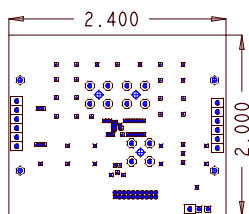


NOTES:

1. PRINTED WIRING BOARD DESIGN AND ACCEPTANCE CRITERIA SHALL BE IAW WITH THE REQUIREMENTS OF IPC-2221 BOARD TYPE 3, PERFORMANCE CLASS 2, AND IPC-A-600 UNLESS SPECIFIED BELOW.
2. MATERIAL - EPOXY GLASS .062 TOTAL THICKNESS +/- 10%, FR4, 1 OZ COPPER.
3. IMMERSION GOLD. 3-5 MICRO INCHES
4. FRONT TO BACK REGISTRATION TO BE WITHIN .005.
5. THE DIAMETER DIMENSION OF ALL PLATED THRU HOLES APPLY AFTER PLATING.
6. ELECTROPLATED COPPER SHALL BE USED FOR PLATED THRU HOLES, AND SHALL HAVE A MINIMUM THICKNESS OF .001 ON THE HOLE WALLS.
7. SOLDER MASK BOTH SIDES USING RED IAW IPC-SM-840.
8. SILKSCREEN BOTH SIDES WITH WHITE NON CONDUCTIVE EPOXY BASED INK.
9. MARK DATE CODE AND MANUFACTURERS IDENTIFICATION ON SOLDER SIDE PER IPC RB 276.
10. PWB MUST BE 100% ELECTRICALLY TESTED FOR SHORTS AND CONTINUITY.

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
✕	8.0	PLATED	11
✕	10.0	PLATED	67
•	23.0	PLATED	19
✕	23.0	PLATED	1
⊞	36.0	PLATED	2
⊞	36.0	PLATED	13
⊞	37.0	PLATED	12
⊞	50.0	PLATED	4
⊞	73.0	PLATED	3



Drill Chart: Top - Bottom

4 Layer Stack-up

Layer Order	Layer Name	Material Type	Thickness (mils)	Copper Weight
1	Top	Copper	1.4	1 OZ
		Prepreg	4	
2	Layer 2	Copper	1.4	1 OZ
		Core	48.4	
3	Layer 3	Copper	1.4	1 OZ
		Prepreg	4	
4	Bottom	Copper	1.4	1 OZ

Final Board Thickness: .062 +/-10%

PHYSICAL BOARD DIMENSIONS & LAYER STRUCTURE

↓	_____	SILK TOP	silkt.art
	_____	MASK TOP	smaskt.art
	_____	COMPONENT	Top.art (1oz)
	_____	LAYER 2	layer2.art (1oz)
	_____	LAYER 3	layer3.art (1oz)
	_____	SOLDER	layer4.art (1oz)
	_____	MASK BOTTOM	smaskb.art
↑	_____	SILK BOTTOM	silkb.art

.062" +/- 10%

ENGINEER: BRAD SUPPANZ	DRAWN BY: PHUONG CAO	BOARD NUMBER: ISL9122A11-EVZ	
RELEASED BY: BRAD SUPPANZ	DATE DRAWN: 06/30/2017	1001 MURPHY RANCH ROAD MILPITAS CA 95035	
UPDATED BY:	DATE RELEASED: 06/30/2017	MASK#	REV. A
interasil		FILENAME: ISL9122A11-EVZ_LAYOUT	SHEET 1